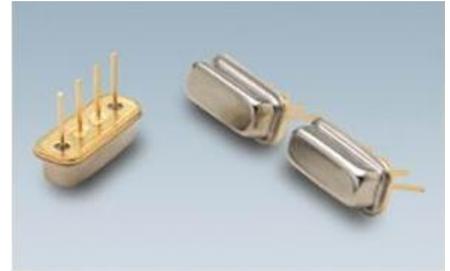


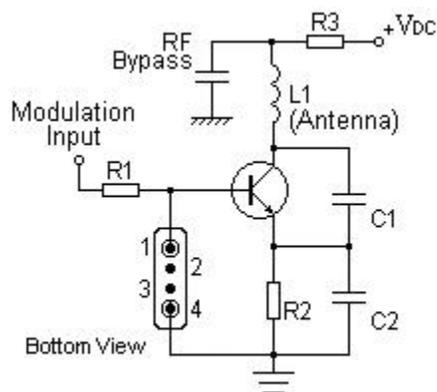
Features

- 1-port Resonator
- Metal Case for **SC04-06**
- **RoHS** compatible
- Package Code SC04-06
- **Electrostatic Sensitive Device(ESD)**

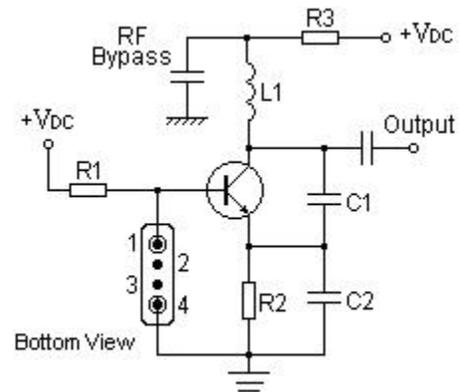


Application

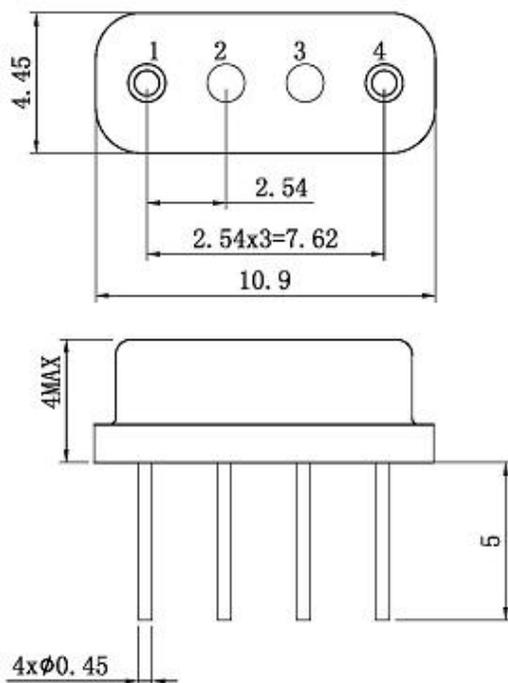
Typical Low-Power Transmitter Application



Typical Local Oscillator Application



Package Dimensions (SC04-06)



Pin Configuration

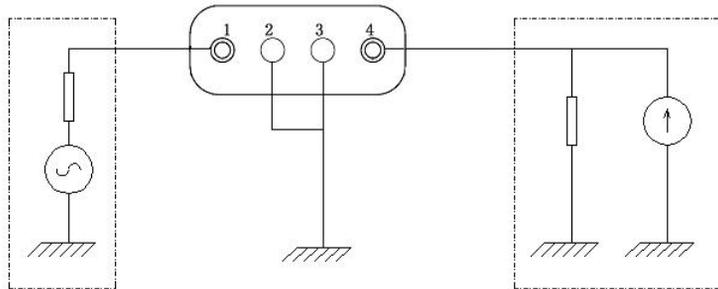
1	Input/ Output
4	Output/ Input
2,3	Case Ground

Marking

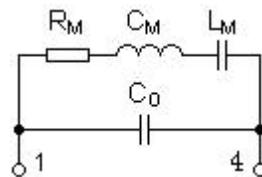


SF	Trademark
R	SAW Resonator
315A	Part number

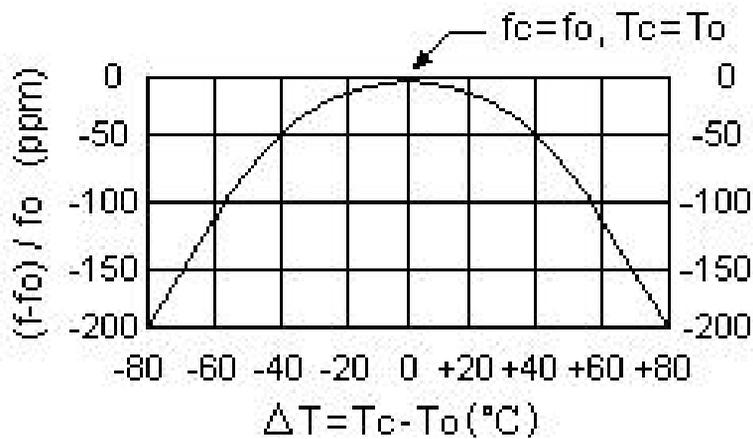
Test Circuit



Equivalent LC Model



Temperature Characteristics



The curve shown above accounts for resonator contribution only and does not include LC component temperature contributions.

Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V_{DC}	± 30	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T_{stg}	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

Electronic Characteristics

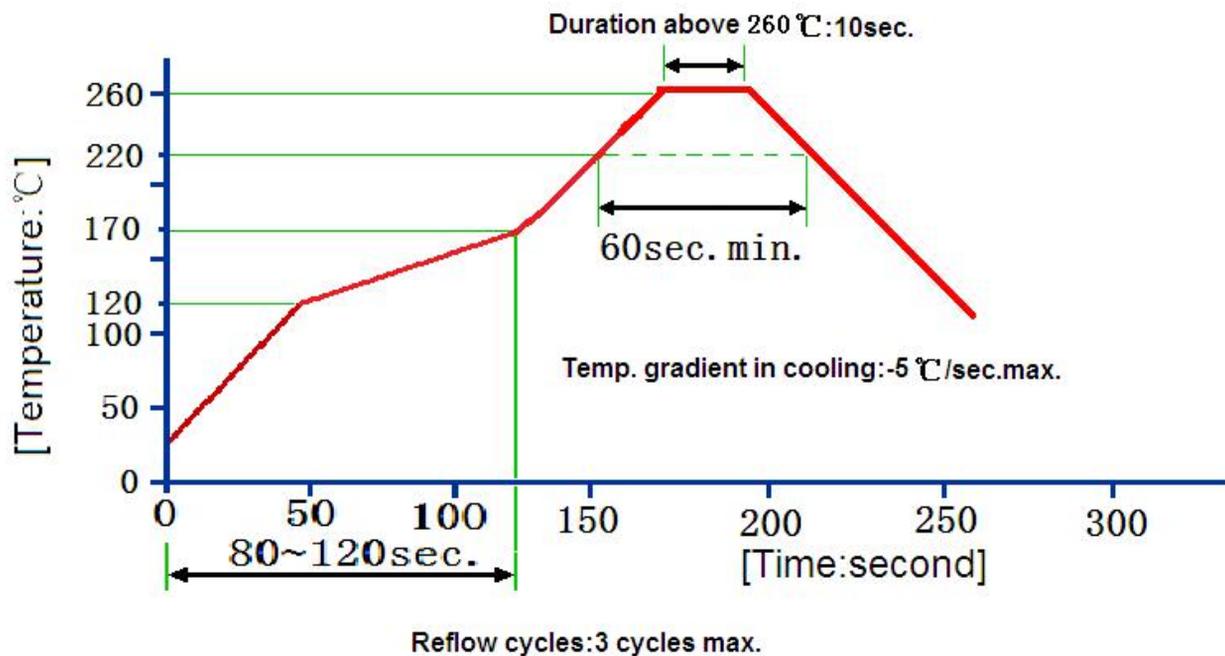
Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

Item			Minimum	Typical	Maximum	Unit
Center Frequency	Absolute Frequency	f_c		315.00		MHz
	Tolerance from 315.00MHz	Δf_c		± 75		KHz
Insertion Loss(min)		IL		1.3	2.0	dB
Quality Factor	Unloaded Q	Q_U		12050		
	50Ω Loaded Q	Q_L		1462		
Temperature Stability	Turnover Temperature	T_0	25	40	55	°C
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C
Frequency Aging	Absolute Value during the First Year	$ f_A $		≤ 10		ppm/yr
DC Insulation Resistance between Any Two Pins			1.0			$M\Omega$
RF Equivalent RLC Model	Motional Resistance	R_M		14	25	Ω
	Motional Inductance	L_M		84.2		μH
	Motional Capacitance	C_M		3.04		fF
	Static Capacitance	C_0	3.3	3.6	3.9	pF

Recommended Reflow Soldering Diagram



Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.